# AC Biasing for End Terminators

Capacitors are used in end-terminations to reduce the quiescent power dissipation.



If the drive circuit spends half its time in each state (also called *DC-balanced*), the average value accumulated on  $C_1$  will be halfway between HI and LO voltages.

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### **AC Biasing for End Terminators**

The voltage across  $R_1$  will be  $\Delta V/2$ . The power dissipated in  $R_1$  will be

$$P_{R1} = \frac{(\Delta V/2)^2}{Z_0} = \frac{\Delta V^2}{4Z_0}$$
 where  
 
$$\Delta V = \text{HI-LO Logic voltages, V}$$
  

$$Z_0 = \text{Value of terminating resistor, }\Omega$$

In the split terminator either  $R_2$  or  $R_3$  always has the full  $\Delta V$  across it, but each resistor is twice as big as  $R_1$  so, the average power dissipation is

$$P_{R_2 + R_3} = \frac{(\Delta V)^2}{2Z_0}$$
 Twice the power of DC-balanced

The additional wasted power dissipation flows from  $V_{CC}$  directly to ground through  $R_2$  and  $R_3$ .

From driving circuit's perspective, the two terminations are indistinguishable w.r.t. power dissipation.

Only the dissipation in the terminating resistors differs.



## **End Terminations for Differential Lines**

Given two signals which are complementary (a differential pair), we can connect their end-terminating resistors together onto a single capacitor.



This provides a power saving end terminator with a guaranteed correct voltage always present on  $C_1$ .

## **Resistor Selection: Accuracy in Terminating Resistors**

Purpose of terminating resistor is to reduce/eliminate unwanted reflections on a Tx-line.



# **Resistor Selection**

This is possible only when its value matches the characteristic impedance of the Tx-line ( $Z_0$ ).

To compute the *worst-case* terminating mismatch, the uncertainty in  $Z_0$  is added to the uncertainty in the terminating resistor.

The uncertainty in Z<sub>0</sub> is usually larger than that of the terminating resistor. E.g., with a 10% uncertainty in Z<sub>0</sub>, designers would use a resistor with a 1% tolerance.

For high fidelity signal requirements, use both source and end terminations. Cuts the received signal in half, but reflections are *greatly* reduced. Also, this relaxes the tolerance required for termination matching at either end.

This technique is used extensively in microwave circuits but for digital electronics, *receivers* must be able to discriminate between reduced levels.



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### **Resistor Selection**

Always calculate the *worst-case* power dissipation in each terminator regardless of the operating speed, i.e., do not assume 50% duty cycle.

Worst case for *split termination* 



#### **Power Dissipation in Terminating Resistors**

Standard 1/8-W resistors will over heat in this case at room temperature. Even 1/4-W resistors may overheat at elevated ambient temperatures.

Power handing capacity of many resistors declines at elevated temperatures.

Resistor bodies have thermal resistance rating (Degree Celsius rise per Watt) just like IC packages.

However, resistors (especially ceramic) can tolerate much higher operating temperatures than ICs.

Unlike IC packages, resistors can be mounted in two different configurations:

Horizontal Mount

### **Power Dissipation in Terminating Resistors**

The vertical mount has a lower thermal resistance in still air than the horizontal mount.

The **VERY** short leg between the resistor and circuit board reduces thermal resistance.

The horizontal mount has a *lower inductance* because the leads stay low.

As a consequence of overheating, the resistance value may drift, causing reflections.

In extreme cases a resistor may crack open, unterminating the circuit.

Along with resistance value, a tolerance, and power rating, the next most important factor is the parasitic *series inductance*.

Every resistor has a parasitic series inductance depending on its internal construction, external lead type, and mounting configuration.





## **Series Inductance of Terminating Resistors**

The effect of series inductance is a function of operating frequency.

The magnitude of inductive reactance seen by a rising edge as a function of rise time is given by:

$$\left|X(T_r)\right| = \frac{\pi L}{T_r}$$

Parasitic inductance causes termination mismatch just like an error in the terminating resistance.

Every 1% of reactance causes 1/2% of reflection.

E.g., when  $|X(T_r)|$  equals 10% of terminating resistance, the reflection is 5%.

Typical series inductance of resistors:

Resistor Type	Series Inductance (nH)	
1/4-W axial	2.5	$2.2\Omega \text{ carbon-film}$ $\rightarrow 0\Omega  0.12'' \times 0.06''$
1/8-W axial	1.0	
1/8-W 1206, surface-mour	nt 0.9	
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# **Series Inductance of Terminating Resistors**

- Lab Experiment using:
- 1/8-W axial resistors to terminate a signal with rise and fall time of 1ns.
- Split termination of 100  $\Omega$  to  $V_{CC}$  (5V) and 100  $\Omega$  to ground.
- Transmission line impedance of  $50\Omega$ .

Magnitude of *inductive reactance*:

$$\left|X(T_r)\right| = \frac{\pi(1nH)}{1ns} = 3.14\Omega$$

Calculate the inductive reactance magnitude to resistance ratio  $|X(T_r)|/R$ :

$$\frac{\left|X(T_r)\right|}{100\Omega} = 3.14\%$$

The reflection due to this inductance is 1.5% because of the parallel, split termination (single terminating resistor of 50 Ohms twice as much -> 3.14% because of 50 in demoninator).

In general, putting resistors in parallel is a good way to make low inductance structures.





### **Effect of Inductance of Terminating Resistance**

When testing a pure inductance, we expect the area of an inductive spike:

$$Area = \frac{L}{R_S} \Delta V$$
  $R_S = \text{Test jig source resistance}$ 

When testing a pure resistance, we expect a step value of:

Final Value = 
$$\frac{R_1}{R_1 + R_S} \Delta V$$
  $R_1$  = Resistance under test

We expect to see both superimposed for a physical resistor.

Use the test jig source resistance and final output value to solve for the unknown resistance ( $R_1$ ) or measure  $R_1$  with a DC ohmmeter.

Subtract the computed output from the measured waveform to obtain the inductive spike.

We can then compute the unknown inductance using:

$$L = (\text{spike area}) \frac{R_1 + R_S}{\Delta V}$$

Accounts for resistance of DUT



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The cross-coupling can be worse than the coupling between adjacent transmission lines.

Crosstalk in terminations is due to both mutual inductive and mutual capacitive coupling (inductive is usually larger).

Both proportional to the derivative of the applied input signal.

Noise Voltage = 
$$\frac{K}{R} \left( \frac{\Delta V}{T_{10} - 90} \right)$$

Noise voltage is peak crosstalk coupled onto trace 2 K = Overall cross-coupling coefficient (ohm-seconds or H)







## **Crosstalk from Adjacent Surface-Mounted Resistors**

They exhibit lower crosstalk coefficient than axial components since they are closer to the board.

To reduce *H* and lower crosstalk, put the ground plane layer near the circuit board outer surface directly underneath the surface-mounted parts.





## **Crosstalk from SIP Terminating Resistors**

Internal wiring has a dramatic impact on single inline packages (SIP).

Overlapping current paths cause inductance loop



Current paths do not overlap Mutual inductance is small



For SIP-A, the current path is shared by all the terminators, increasing mutual inductance between resistors in the package.

For SIP-B, each resistor has a separate return pin improving its performance by a factor of 100.

